

# SN54HC32, SN74HC32 QUADRUPLE 2-INPUT POSITIVE-OR GATES

SCLS200B – DECEMBER 1982 – REVISED MAY 1997

- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

## description

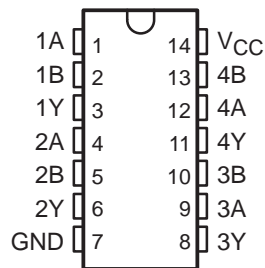
These devices contain four independent 2-input OR gates. They perform the Boolean function  $Y = \overline{A} \cdot \overline{B}$  or  $Y = A + B$  in positive logic.

The SN54HC32 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74HC32 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

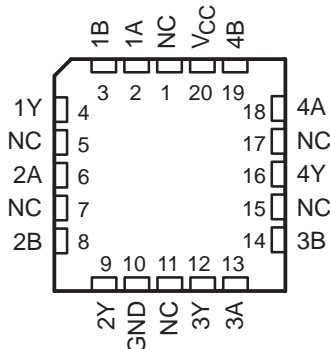
FUNCTION TABLE  
(each gate)

INPUTS		OUTPUT
A	B	Y
H	X	H
X	H	H
L	L	L

SN54HC32 . . . J OR W PACKAGE  
SN74HC32 . . . D, DB, N, OR PW PACKAGE  
(TOP VIEW)

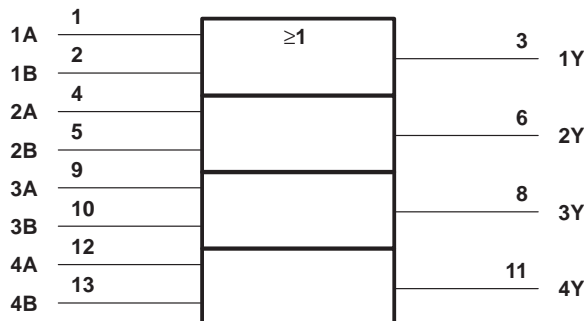


SN54HC32 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, DB, J, N, PW, and W packages.

## logic diagram (positive logic)



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
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# SN54HC32, SN74HC32

## QUADRUPLE 2-INPUT POSITIVE-OR GATES

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### absolute maximum ratings over operating free-air temperature†

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1) .....	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 25$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 50$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package .....	127°C/W
DB package .....	158°C/W
N package .....	78°C/W
PW package .....	170°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

### recommended operating conditions

		SN54HC32			SN74HC32			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	2	5	6	2	5	6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2$ V		1.5	1.5		V	
		$V_{CC} = 4.5$ V		3.15	3.15			
		$V_{CC} = 6$ V		4.2	4.2			
$V_{IL}$	Low-level input voltage	$V_{CC} = 2$ V		0	0.5	0	0.5	V
		$V_{CC} = 4.5$ V		0	1.35	0	1.35	
		$V_{CC} = 6$ V		0	1.8	0	1.8	
$V_I$	Input voltage	0		$V_{CC}$	0		$V_{CC}$	V
$V_O$	Output voltage	0		$V_{CC}$	0		$V_{CC}$	V
$t_t$	Input transition (rise and fall) time	$V_{CC} = 2$ V		0	1000	0	1000	ns
		$V_{CC} = 4.5$ V		0	500	0	500	
		$V_{CC} = 6$ V		0	400	0	400	
$T_A$	Operating free-air temperature	-55		125	-40		85	°C



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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC32		SN74HC32		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 μA	2 V	1.9	1.998		1.9		1.9	V	
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		I <sub>OH</sub> = -4 mA	4.5 V	3.98	4.3		3.7		3.84		
		I <sub>OH</sub> = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		I <sub>OL</sub> = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I <sub>OL</sub> = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0		6 V		±0.1	±100		±1000		±1000	nA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0		6 V			2		40		20	μA
C <sub>i</sub>			2 V to 6 V		3	10		10		10	pF

**switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC32		SN74HC32		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	Y	2 V		50	100		150		125	ns
			4.5 V		10	20		30		25	
			6 V		8	17		25		21	
t <sub>t</sub>		Y	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

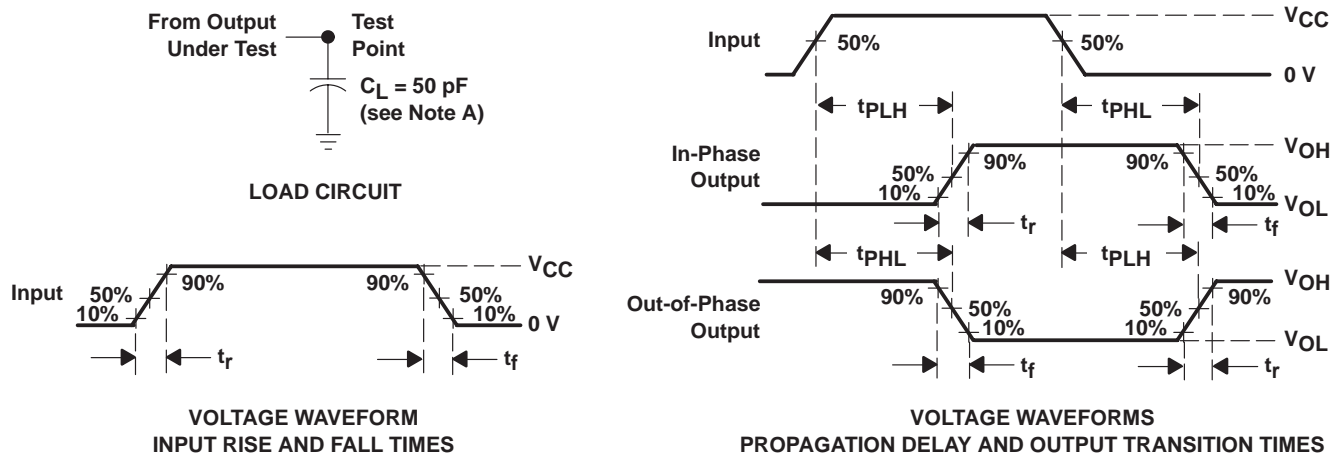
**operating characteristics, T<sub>A</sub> = 25°C**

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance per gate	No load	20	pF

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## PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A.  $C_L$  includes probe and test-fixture capacitance.
  - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r = 6 \text{ ns}$ ,  $t_f = 6 \text{ ns}$ .
  - C. The outputs are measured one at a time with one input transition per measurement.
  - D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

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